

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Chun Hung LIN

Serial No. 09/854,487

Filed: May 15, 2001

Group Art Unit: 2823

Examiner: D. Collins



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TECHNOLOGY CENTER 2800

For: LOW-PIN-COUNT CHIP PACKAGE AND MANUFACTURING METHOD THEREOF

COMMISSIONER FOR PATENTS

Washington, D.C. 20231

Dear Sir:

Transmitted herewith is an Amendment in the above identified application.

☒ No additional fee is required.☐ Small entity status of this application has been established.☐ A verified statement to establish small entity status under 37 CFR 1.9 and 1.27 is enclosed.☐ Also attached:

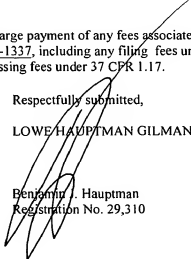
The fee has been calculated as shown below:

	NO. OF CLAIMS	HIGHEST PREVIOUSLY PAID FOR	EXTRA CLAIMS	RATE	FEE
Total Claims	16	20	0	x \$ 18 =	\$ 0.00
Independent Claims	2	3	0	x \$ 80 =	\$ 0.00
If multiple claims newly presented, add \$260.00					\$0.00
Fee for extension of time					\$0.00
TOTAL FEE DUE					\$ 0.00

☐ A check in the amount of \$0.00 is attached☒ The Commissioner is hereby authorized to charge payment of any fees associated with this communication or credit any overpayment, to Deposit Account No. 07-1337, including any filing fees under 37 CFR 1.16 for presentation of extra claims and any patent application processing fees under 37 CFR 1.17.

Respectfully submitted,

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 Date: September 9, 2002
 BJH/cw

Docket No.: 4459-018A



PATENT

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Chun Hung LIN :
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AMENDMENT

COMMISSIONER FOR PATENTS
Washington, D. C. 20231

Sir:

The following amendments and remarks are submitted in response to the Official Action dated June 14, 2002.

IN THE CLAIMS:

Please add new claims as follows:

-- 15. The chip package of claim 4, wherein each of the die pad and connection pads is a piece made of a single material which projects integrally from within the package body outwardly and beyond a bottom surface of the package body.

16. The chip package of claim 15, wherein said single material is copper.

17. The chip package of claim 15, wherein said piece has a first portion embedded in the package body and a second portion located outside the package body, said second portion